SL2S2002; SL2S2102

ICODE SLIX

Rev. 3.3 — 23 August 2012
178033

Product data sheet
COMPANY PUBLIC

1. General description

The ICODE SLIX IC is a dedicated chip for intelligent label applications such as libraries, product authentication in different industries such as pharmaceutical, medical devices and alcohol, as well as production management in different areas of the industry. This IC is the third generation of a product family of smart label ICs based on the ISO standards ISO/IEC 15693 (Ref. 1) and ISO/IEC 18000-3 (Ref. 4), prolonging a successful story of NXP in the field of vicinity identification systems.

The ICODE system offers the possibility of operating labels simultaneously in the field of the reader antenna (anticollision). It is designed for long range applications.

1.1 Contactless energy and data transfer

Whenever connected to a very simple and easy-to-produce type of antenna (as a result of the 13.56 MHz carrier frequency) made out of a few windings printed, winded, etched or punched coil, the ICODE SLIX IC can be operated without line of sight up to a distance of 1.5 m (gate width). No battery is needed. When the smart label is positioned in the field of an interrogator antenna, the high speed RF communication interface enables data to be transmitted up to 53 kbit/s.

1.2 Anticollision

An intelligent anticollision function enables several tags to operate in the field simultaneously. The anticollision algorithm selects each tag individually and ensures that the execution of a transaction with a selected tag is performed correctly without data corruption resulting from other tags in the field.

1.3 Security and privacy aspects

- Unique IDentifier (UID):

  The UID cannot be altered and guarantees the uniqueness of each label.

- Password protected EAS and AFI functionality:

  The 32-bit EAS/AFI password enables the addressed label to be set in a mode where the EAS status and the AFI value can only be changed if the correct EAS/AFI password is transmitted to the label within the mentioned commands.

2. Features and benefits

2.1 ICODE SLIX RF interface (ISO/IEC 15693)

- Contactless transmission of data and supply energy (no battery needed)
- Operating distance: up to 1.5 m (depending on antenna geometry)
- Operating frequency: 13.56 MHz (ISM, world-wide licence freely available)
- Fast data transfer: up to 53 kbit/s
- High data integrity: 16-bit CRC, framing
- True anticollision
- Password protected Electronic Article Surveillance (EAS)
- Password protected Application Family Identifier (AFI)
- Data Storage Format Identifier (DSFID)
- Additional fast anticollision read
- Write distance equal to read distance

2.2 EEPROM

- 1024 bits, organized in 32 blocks of 4 bytes each
- 50 years data retention
- Write endurance of 100000 cycles

2.3 Security

- Unique identifier for each device
- Lock mechanism for each user memory block (write protection)
- Lock mechanism for DSFID, AFI, EAS
- Password (32-bit) protected EAS and AFI functionality

3. Applications

- Libraries
- Item level tagging in pharmaceutical supply chains
- Counterfeit protection for consumer goods
- Industrial applications
- Asset and document tracking

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4. Ordering information

Table 1. Ordering information

Type number	Package		Version
	Name	Description	
SL2S2002FUD	wafer	sawn, bumped wafer, 120 μm, on film frame carrier, C_i between LA and LB = 23.5 pF (typical)	-
SL2S2102FUD	wafer	sawn, bumped wafer, 120 μm, on film frame carrier, C_i between LA and LB = 97 pF (typical)	-
SL2S2002FTB	XSON3	plastic extremely thin small outline package; no leads; 3 terminals; body 1 x 1.45 x 0.5 mm; C_i between LA and LB = 23.5 pF (typical)	SOT1122
SL2S2102FTB	XSON3	plastic extremely thin small outline package; no leads; 3 terminals; body 1 x 1.45 x 0.5 mm; C_i between LA and LB = 97 pF (typical)	SOT1122

5. Block diagram

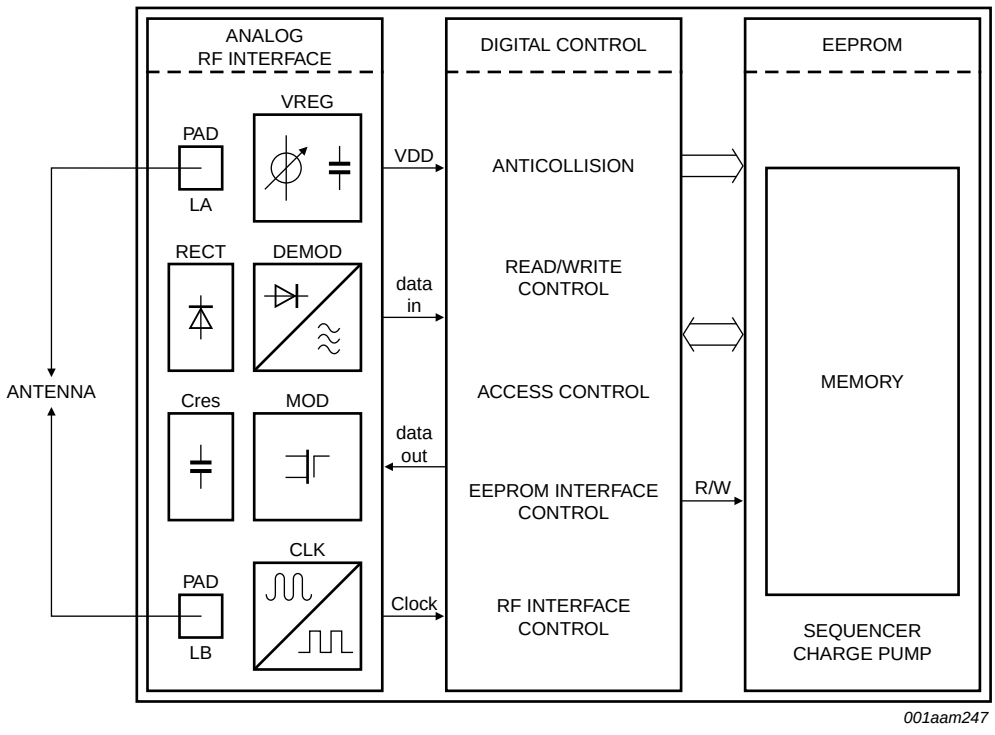

Fig 1. Block diagram of ICODE SLIX

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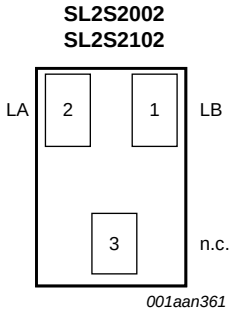
6. Pinning information



Transparent top view

Fig 2. Pin configuration for SOT1122

Table 2. Pin description SOT1122

Pin	Symbol	Description
1	LB	antenna RF input
2	LA	antenna RF input
3	n.c.	not connected

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7. Wafer layout

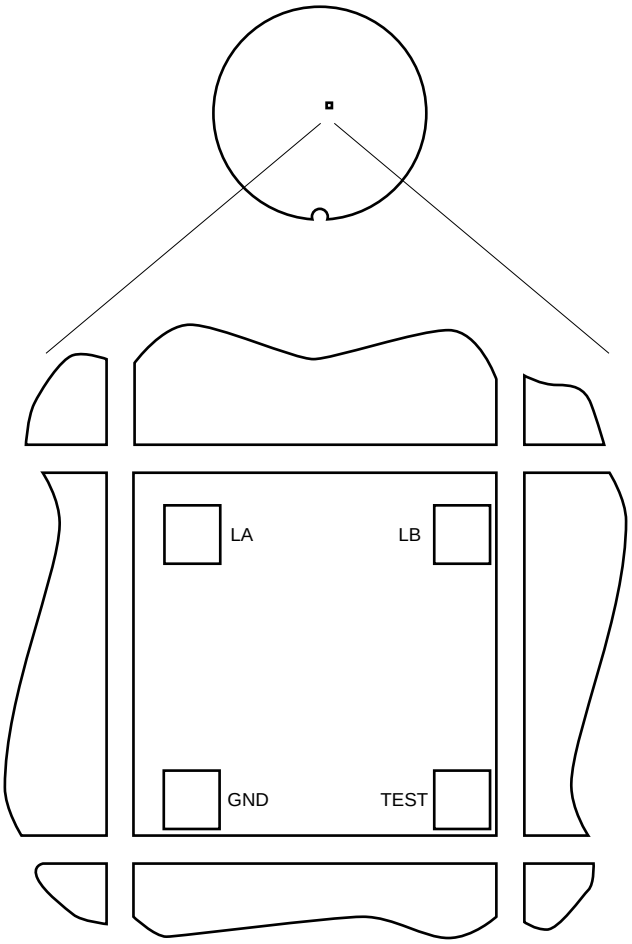

Fig 3. Wafer SL2S2002FUD layout and pin configuration for the bare die

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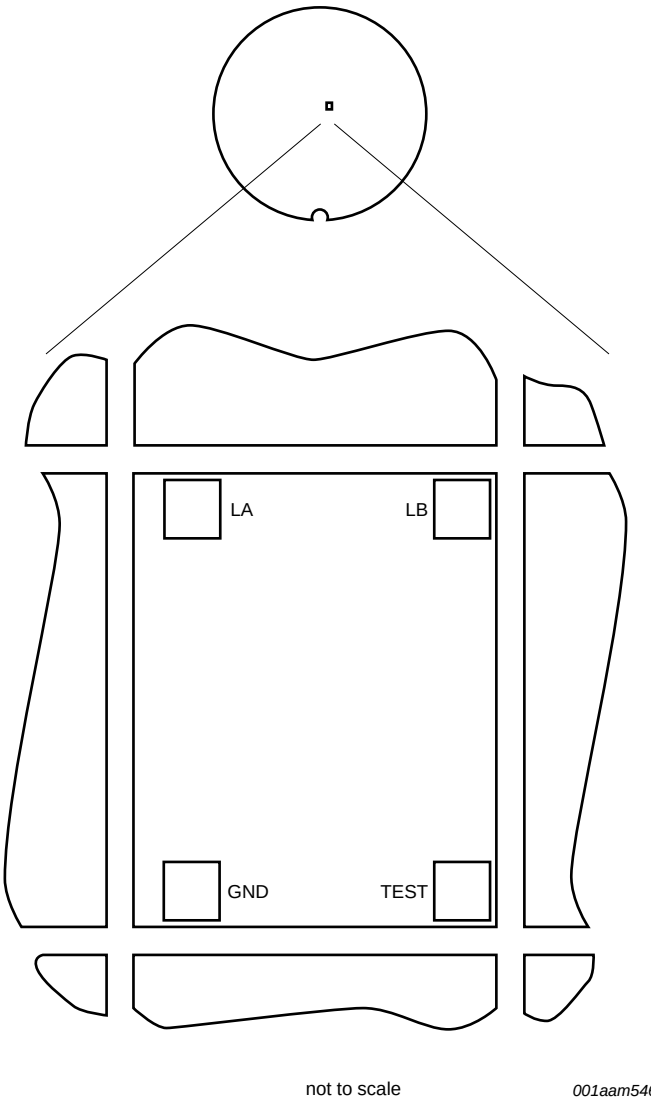

Fig 4. Wafer SL2S2102FUD layout and pin configuration for the bare die

7.1 Bonding pad description

Table 3. Bonding pad description

Symbol	Description
LA	antenna RF input
LB	antenna RF input
GND	ground
TEST	test input

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8. Mechanical specification

8.1 Wafer specification

See Ref. 6 “General specification for 8” wafer on UV-tape with electronic fail die marking”.

Table 4. Wafer specification

Wafer	
Designation	each wafer is enscribed with batch number and wafer number
Diameter	200 mm (8 inches)
Thickness	120 μm ± 15 μm
Process	CMOS 0.14 μm
Batch size	25 wafers
Dies per wafer	
SL2S2002FUD	110050
SL2S2102FUD	88225
Wafer backside	
Material	Si
Treatment	ground and stress release
Roughness	R_a minimum = 0.5 μm
	R_t maximum = 5 μm
Chip dimensions	
Die size without scribe	
SL2S2002FUD	520 μm × 484 μm = 251680 mm^2
SL2S2102FUD	520 μm × 607 μm = 315640 mm^2
Scribe line width	
X-dimension	15 μm (scribe line width measured between nitride edges)
Y-dimension	15 μm (scribe line width measured between nitride edges)
Number of pads	4
Pad location	non-diagonal/placed in chip corners
Distance pad to pad LA to LB	400 μm
Distance pad to pad LB to TEST	
SL2S2002FUD	360 μm
SL2S2102FUD	517 μm
Passivation on front	
Type	sandwich structure
Material	PE-nitride (on top)
Thickness	1.75 μm total thickness of passivation
Au bump	
Material	>99.9 % pure Au
Hardness	35 HV to 80 HV 0.005
Shear strength	>70 MPa
Height	18 μm
Height uniformity	

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Table 4. Wafer specification

within a die	±2 μm
within a wafer	±3 μm
wafer to wafer	±4 μm
Bump flatness	±1.5 μm
Bump size	
LA, LB	60 μm × 60 μm
TEST, GND	60 μm × 60 μm
variation	±5 μm
Under bump metallization	sputtered TiW

8.1.1 Fail die identification

No inkdots are applied to the wafer.

Electronic wafer mapping (SECS II format) covers the electrical test results and additionally the results of mechanical/visual inspection.

See Ref. 6 “General specification for 8” wafer on UV-tape with electronic fail die marking”.

8.1.2 Map file distribution

See Ref. 6 “General specification for 8” wafer on UV-tape with electronic fail die marking”.

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9. Functional description

9.1 Block description

The ICODE SLIX IC consists of three major blocks:

- Analog RF interface
- Digital controller
- EEPROM

The analog section provides stable supply voltage and demodulates data received from the reader for processing by the digital section. The analog section's modulation transistor also transmits data back to the reader.

The digital section includes the state machines, processes the protocol and handles communication with the EEPROM.

The label requires no internal power supply. Its contactless interface generates the power supply and the system clock via the resonant circuitry by inductive coupling to the interrogator. The interface also demodulates data that are transmitted from the interrogator to the ICODE Label, and modulates the electromagnetic field for data transmission from the ICODE Label to the interrogator.

Data are stored in a non-volatile memory (EEPROM).

9.2 Memory organization

The 1024 bit EEPROM memory is divided into 32 blocks. A block is the smallest access unit. Each block consists of 4 bytes (1 block = 32 bits). Bit 0 in each byte represents the least significant bit (LSB) and bit 7 the most significant bit (MSB), respectively.

The memory is divided into 2 parts:

- Configuration area

  Within this part of the memory all required information is stored, such as UID, write protection, access control information, passwords, AFI and EAS. This memory area cannot be directly accessed.

- User memory

  Within the 896 bit memory area the user data are stored. Direct read/write access to this part of the memory is possible depending on the related write protection conditions.

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Table 5. Memory organization

Block	Byte 0	Byte 1	Byte 2	Byte 3	Description
					Configuration area for internal use
0					User memory:
1					28 blocks,
2					4 bytes each,
:	:	:	:	:	112 bytes in total.
25					
26					
27					

Blocks 0 to 27 can be addressed with read and write commands only.

9.2.1 Unique identifier

The 64-bit unique identifier (UID) is programmed during the production process according to ISO/IEC 15693-3 and cannot be changed afterwards.

The 64 bits are numbered according to ISO/IEC 15693-3 starting with LSB 1 and ending with MSB 64. This is in contrast to the general used bit numbering within a byte.

The TAG type is a part of the UID (bit 41 to 48, next to the manufacturer code which is “04h” for NXP Semiconductors).

The TAG type of the ICODE SLIX IC is “01h”.

Bit 37 is set to logic 1 for the ICODE SLIX IC which indicates that this type supports the password protected EAS/AFI feature (not supported by ICODE SLI SL2ICS2001 with bit 37 set to logic 0).

Table 6. Unique identifier

MSB							LSB
64:57	56:49	48:41	40:1				
“E0”	“04”	“01”	IC manufacturer serial number				
UID 7	UID 6	UID 5	UID 4	UID 3	UID 2	UID 1	UID 0

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9.2.2 Configuration of delivered ICs

ICODE SLIX ICs are delivered with the following configuration by NXP Semiconductors:

- Unique identifier is unique and read only
- Write access conditions allow change to user blocks, AFI, DSFID, EAS and passwords
- Status of EAS mode is not defined
- AFI is supported and not defined
- All EAS/AFI password bytes are 00h
- EAS and AFI password protection is disabled
- DSFID is supported and not defined
- User data memory is not defined

Remark: Because the EAS mode is undefined at delivery, the EAS mode shall be set (enabled or disabled) according to your application requirements during the test or initialization phase.

Remark: If EAS and/or AFI password protection is not required in the targeted application, it is recommended a random EAS/AFI password is written during the label initialization.

9.3 Communication principle

For detailed description of the protocol and timing please refer to ISO/IEC 15693-2 (modulation, bit-coding, framing, Ref. 2) and ISO/IEC 15693-3 (anticollision, timing, protocol, Ref. 3).

9.4 Supported commands

9.4.1 Mandatory commands

9.4.1.1 INVENTORY

As defined in ISO/IEC 15693-3.

9.4.1.2 STAY QUIET

As defined in ISO/IEC 15693-3.

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9.4.2 Optional commands

9.4.2.1 READ SINGLE BLOCK

As defined in ISO/IEC 15693-3.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

9.4.2.2 WRITE SINGLE BLOCK

As defined in ISO/IEC 15693-3.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

9.4.2.3 LOCK BLOCK

As defined in ISO/IEC 15693-3.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

9.4.2.4 READ MULTIPLE BLOCKS

As defined in ISO/IEC 15693-3.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

Remark: If the sum of the first block number and the number of blocks exceeds the total available number of user blocks, the number of transmitted blocks is less than the requested number of blocks, which means that the last returned block is the highest available user block, followed by the 16-bit CRC and the EOF.

9.4.2.5 SELECT

As defined in ISO/IEC 15693-3.

9.4.2.6 RESET TO READY

As defined in ISO/IEC 15693-3.

9.4.2.7 WRITE AFI

As defined in ISO/IEC 15693-3.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

Remark: This command maybe password protected, refer to Section 9.4.3.11 “PASSWORD PROTECT EAS/AFI”.

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9.4.2.8 LOCK AFI

As defined in ISO/IEC 15693-3.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

Remark: This command maybe password protected, refer to Section 9.4.3.11 "PASSWORD PROTECT EAS/AFI".

9.4.2.9 WRITE DSFID

As defined in ISO/IEC 15693-3.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

9.4.2.10 LOCK DSFID

As defined in ISO/IEC 15693-3.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

9.4.2.11 GET SYSTEM INFORMATION

As defined in ISO/IEC 15693-3.

The TAG type of the ICODE SLIX is "01h".

9.4.2.12 GET MULTIPLE BLOCK SECURITY STATUS

As defined in ISO/IEC 15693-3.

Remark: If the sum of the first block number and the number of blocks exceeds the total available number of user blocks the number of transmitted security status bytes is less than the requested number, which means that the last returned status byte is the one corresponding to the highest available user block, followed by the 16-bit CRC and the EOF.

9.4.3 Custom commands

The manufacturer code of NXP Semiconductors is defined in ISO/IEC 7816-6A1 (Ref. 5). It has the value "04h".

For the structure of custom commands please refer to ISO/IEC 15693-3.

If not explicitly specified differently all address modes are supported.

9.4.3.1 GET RANDOM NUMBER

Command code = B2h

The GET RANDOM NUMBER command is required to receive a random number from the label IC. The passwords that will be transmitted with the SET PASSWORD command have to be calculated with the password and the random number (see Section 9.4.3.2 "SET PASSWORD").

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The different passwords are addressed with the password identifier.

Table 7. Request format

SOF	Flags	GET RANDOM NUMBER	IC Mfg code	UID	CRC16	EOF
-	8 bits	8 bits	8 bits	64 bits optional	16 bits	-

Table 8. Response format when Error_flag set

SOF	Flags	Error code	CRC16	EOF
-	8 bits	8 bits	16 bits	-

Table 9. Response format when Error_flag NOT set

SOF	Flags	Random number	CRC16	EOF
-	8 bits	16 bits	16 bits	-

9.4.3.2 SET PASSWORD

Command code = B3h

The SET PASSWORD command enables the EAS/AFI password to be transmitted to the label to access EAS and/or AFI (if the EAS and/or AFI password is enabled). The SET PASSWORD command has to be executed just once for the related password if the label is powered.

Remark: The SET PASSWORD command can only be executed in Addressed or Selected mode.

The XOR password has to be calculated with the password and two times the received random number from the last GET RANDOM NUMBER command:

XOR_Password[31:0] = Password[31:0] XOR {Random_Number[15:0], Random_Number[15:0]}.

The EAS/AFI password is addressed with the password identifier.

Table 10. Request format

SOF	Flags	SET PASSWORD	IC Mfg code	UID	Password identifier	XOR password	CRC16	EOF
-	8 bits	8 bits	8 bits	64 bits optional	8 bits	32 bits	16 bits	-

Table 11. Password Identifier

Password identifier	Password
10h	EAS/AFI

Table 12. Response format when Error_flag set

SOF	Flags	Error code	CRC16	EOF
-	8 bits	8 bits	16 bits	-

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Table 13. Response format when Error_flag NOT set

SOF	Flags	CRC16	EOF
-	8 bits	16 bits	-

Remark: If the IC receives an invalid password, it will not execute any following command until a Power-On Reset (POR) (RF reset) is executed.

9.4.3.3 WRITE PASSWORD

Command code = B4h

The WRITE PASSWORD command enables a new password to be written into the related memory if the related old password has already been transmitted with a SET PASSWORD command and the addressed password is not locked (see Section 9.4.3.4 “LOCK PASSWORD”).

Remark: The WRITE PASSWORD command can only be executed in addressed or selected mode. The new password takes effect immediately which means that the new password has to be transmitted with the SET PASSWORD command to access protected blocks.

The EAS/AFI password is addressed with the password identifier.

The timing of the command is write alike.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

Table 14. Request format

SOF	Flags	WRITE PASSWORD	IC Mfg code	UID	Password identifier	Password	CRC16	EOF
-	8 bits	8 bits	8 bits	64 bits optional	8 bits	32 bits	16 bits	-

Table 15. Password identifier

Password identifier	Password
10h	EAS/AFI

Table 16. Response format when Error_flag set

SOF	Flags	Error code	CRC16	EOF
-	8 bits	8 bits	16 bits	-

Table 17. Response format when Error_flag NOT set

SOF	Flags	CRC16	EOF
-	8 bits	16 bits	-

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9.4.3.4 LOCK PASSWORD

Command code = B5h

The LOCK PASSWORD command enables the addressed password to be locked if the related password has already been transmitted with a SET PASSWORD command. A locked password cannot be changed.

The EAS/AFI password is addressed with the password identifier.

The timing of the command is write alike.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

Table 18. Request format

SOF	Flags	LOCK PASSWORD	IC Mfg code	UID	Password identifier	CRC16	EOF
-	8 bits	8 bits	8 bits	64 bits optional	8 bits	16 bits	-

Table 19. Password identifier

Password identifier	Password
10h	EAS/AFI

Table 20. Response format when Error_flag set

SOF	Flags	Error code	CRC16	EOF
-	8 bits	8 bits	16 bits	-

Table 21. Response format when Error_flag NOT set

SOF	Flags	CRC16	EOF
-	8 bits	16 bits	-

9.4.3.5 INVENTORY READ

Command code = A0h

When receiving the INVENTORY READ request, the ICODE SLIX IC performs the same as the anticollision sequence, with the difference that instead of the UID and the DSFID, the requested memory content is re-transmitted from the ICODE SLIX IC.

If an error is detected, the ICODE SLIX IC remains silent.

If the Option flag is set to logic 0, n blocks of data are re-transmitted. If the Option flag is set to 1, n blocks of data and the part of the UID which is not part of the mask are re-transmitted.

The request contains:

- Flags
- INVENTORY READ command code
- IC manufacturer code

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- AFI (if AFI flag set)
- Mask length
- Mask value (if mask length > 0)
- First block number to be read
- Number of blocks to be read
- CRC 16

Table 22. Request format

SOF	Flags	INVENTORY READ	IC Mfg code	AFI	Mask length	Mask value	First block number	Number of blocks	CRC16	EOF
-	8 bits	8 bits	8 bits	8 bits optional	8 bits	0 to 64 bits	8 bits	8 bits	16 bits	-

The Inventory_flag must be set to logic 1.

The meaning of flags 5 to 8 is in accordance with table 5 in ISO/IEC 15693-3.

The number of blocks in the request is one less than the number of blocks that the ICODE SLIX IC returns in its response.

If the Option flag in the request is set to logic 0 the response contains:

Table 23. Response format: Option flag logic 0

SOF	Flags	Data	CRC16	EOF
-	8 bits	Block length	16 bits	-
		Repeated as needed		

The ICODE SLIX IC reads the requested block(s) and sends back their value in the response. The mechanism and timing of the INVENTORY READ command performs the same as the INVENTORY command which is described in clause 8 of ISO/IEC 15693-3.

If the Option flag in the request is set to logic 1, the response contains:

Table 24. Response format: Option flag logic 1

SOF	Flags	Rest of UID which is not part of the mask and slot number	Data	CRC16	EOF
-	8 bits	0 to 64 bit	Block length	16 bits	-
		Multiple of 8 bits	Repeated as needed		

The ICODE SLIX IC reads the requested block(s) and sends back their value in the response. Additionally the bytes of the UID, which are not parts of the mask and the slot number in case of 16 slots, are returned. Instead of padding with zeros up to the next byte boundary, the corresponding bits of the UID are returned. The mechanism and timing of the INVENTORY READ command perform the same as the INVENTORY command which is described in clause 8 of ISO/IEC 15693-3.

Remark: The number of bits of the re-transmitted UID can be calculated as follows:

- 16 slots: 60 bits (bit 64 to bit 4) - mask length rounded up to the next byte boundary
- 1 slot: 64 bits - mask length rounded up to the next byte boundary

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Remark: If the sum of first block number and number of blocks exceeds the total available number of user blocks, the number of transmitted blocks is less than the requested number of blocks, which means that the last returned block is the highest available user block, followed by the 16-bit CRC and the EOF.

Example: mask length = 30 bits

Returned: bit 64 to bit 4 (30 bits) = 30 gives 4 bytes

Table 25. Example: mask length = 30

Byte 0	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7	UID
mask value including padding with zeros				-				transmitted by interrogator
				returned value				transmitted by ICODE SLIX IC

9.4.3.6 FAST INVENTORY READ

Command code = A1h

When receiving the FAST INVENTORY READ command the ICODE SLIX IC behaves the same as the INVENTORY READ command with the following exceptions:

The data rate in the direction ICODE SLIX IC to the interrogator is twice that defined in ISO/IEC 15693-3 depending on the Datarate_flag 53 kbit (high data rate) or 13 kbit (low data rate).

The data rate from the interrogator to the ICODE SLIX IC and the time between the rising edge of the EOF from the interrogator to the ICODE SLIX IC remain unchanged (stay the same as defined in ISO/IEC 15693-3).

In the ICODE SLIX IC to the interrogator direction, only the single subcarrier mode is supported.

9.4.3.7 SET EAS

Command code = A2h

The SET EAS command enables the EAS mode if the EAS mode is not locked. If the EAS mode is password protected the EAS password has to be first transmitted with the SET PASSWORD command.

The timing of the command is write alike.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

Table 26. Request format

SOF	Flags	SET EAS	IC Mfg code	UID	CRC16	EOF
-	8 bits	8 bits	8 bits	64 bits optional	16 bits	-

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Table 27. Response format when Error_flag set

SOF	Flags	Error code	CRC16	EOF
-	8 bits	8 bits	16 bits	-

Table 28. Response format when Error_flag NOT set

SOF	Flags	CRC16	EOF
-	8 bits	16 bits	-

9.4.3.8 RESET EAS

Command code = A3h

The RESET EAS command disables the EAS mode if the EAS mode is not locked. If the EAS mode is password protected the EAS password has to be first transmitted with the SET PASSWORD command.

The timing of the command is write alike.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

Table 29. Request format

SOF	Flags	RESET EAS	IC Mfg code	UID	CRC16	EOF
-	8 bits	8 bits	8 bits	64 bits optional	16 bits	-

Table 30. Response format when Error_flag set

SOF	Flags	Error code	CRC16	EOF
-	8 bits	8 bits	16 bits	-

Table 31. Response format when Error_flag NOT set

SOF	Flags	CRC16	EOF
-	8 bits	16 bits	-

9.4.3.9 LOCK EAS

Command code = A4h

The LOCK EAS command locks the current state of the EAS mode and the EAS ID. If the EAS mode is password protected the EAS password has to be first transmitted with the SET PASSWORD command.

The timing of the command is write alike.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

Table 32. Request format

SOF	Flags	LOCK EAS	IC Mfg code	UID	CRC16	EOF
-	8 bits	8 bits	8 bits	64 bits optional	16 bits	-

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Table 33. Response format when Error_flag set

SOF	Flags	Error code	CRC16	EOF
-	8 bits	8 bits	16 bits	-

Table 34. Response format when Error_flag NOT set

SOF	Flags	CRC16	EOF
-	8 bits	16 bits	-

9.4.3.10 EAS ALARM

Command code = A5h

If the EAS mode is enabled, the EAS sequence is returned from the ICODE SLIX IC.

Table 35. Request format

SOF	Flags	EAS ALARM	IC Mfg code	UID	CRC16	EOF
-	8 bits	8 bits	8 bits	64 bits optional	16 bits	-

If an error is detected the ICODE SLIX IC remains silent.

Table 36. Response format

SOF	Flags	EAS sequence	CRC16	EOF
-	8 bits	256 bits	16 bits	-

EAS sequence (starting with the LSB, which is transmitted first; read from left to right):

```
11110100  11001101  01000110  00001110  10101011  11100101  00001001  11111110
00010111  10001101  00000001  00011100  01001011  10000001  10010010  01101110
01000001  01011011  01011001  01100001  11110110  11110101  11010001  00001101
10001111  00111001  10001011  01001000  10100101  01001110  11101100  11110111
```

If the EAS mode is disabled the ICODE SLIX IC remains silent.

9.4.3.11 PASSWORD PROTECT EAS/AFI

Command code = A6h

The PASSWORD PROTECT EAS/AFI command enables the password protection for EAS and/or AFI if the EAS/AFI password is first transmitted with the SET PASSWORD command.

Option flag set to logic 0: EAS will be password protected.

Option flag set to logic 1: AFI will be password protected.

Both password protections (AFI and EAS) can be enabled separately.

Remark: Independent of the Option flag, this write-alike command will be executed like a write command with Option flag 0 (Option flag not set).

Once the EAS/AFI password protection is enabled, it is not possible to change back to unprotected EAS and/or AFI.

The timing of the command is write alike (as write command with Option flag 0).

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Table 37. Request format

SOF	Flags	PASSWORD PROTECT EAS/AFI	IC Mfg code	UID	CRC16	EOF
-	8 bits	8 bits	8 bits	64 bits optional	16 bits	-

Table 38. Response format when Error_flag set

SOF	Flags	Error code	CRC16	EOF
-	8 bits	8 bits	16 bits	-

Table 39. Response format when Error_flag NOT set

SOF	Flags	CRC16	EOF
-	8 bits	16 bits	-

9.5 Error handling

9.5.1 Transmission errors

According to ISO/IEC 15693 the label IC will not respond if a transmission error (CRC, bit coding, bit count, wrong framing) is detected and will silently wait for the next correct received command.

9.5.2 Not supported commands or options

If the received command or option is not supported, the behavior of the label IC depends on the addressing mechanism.

9.5.2.1 Non Addressed Mode

The label IC remains silent.

9.5.2.2 Addressed or Selected Mode

The addressed or selected label IC responds with the error code “0Fh” (error with no information given or error code is not supported).

If the Inventory flag or the Protocol Extension flag is set, the label IC will not respond if the command or option is not supported.

9.5.3 Parameter out of range

9.5.3.1 Read commands

If the sum of the first block number and the number of blocks exceeds the total available number of user blocks, the number of transmitted blocks is less than the requested number of blocks, which means that the last returned block is the highest available user block, followed by the 16-bit CRC and the EOF.

9.5.3.2 Write and lock commands

If the address of a block to be written does not exist or a block to be written is locked, the behaviour of the label IC depends on the addressing mechanism.

Non Addressed Mode

- The label IC remains silent and aborts the command without writing anything.

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Addressed or Selected Mode

- The addressed or selected label IC responds with the error code “0Fh”(error with no information given or error code is not supported).

9.6 Data integrity

Following mechanisms are implemented in the contactless communication link between interrogator and label to ensure very reliable data transmission:

- 16-bit CRC per block
- Bit count checking
- Bit coding to distinguish between logic 1, logic 0, and no information
- Channel monitoring (protocol sequence and bit stream analysis)

9.7 RF interface

The definition of the RF interface is according to the standard ISO/IEC 15693-2 and ISO/IEC 15693-3.

10. Limiting values

Table 40. Limiting values (Wafer)[1][2]

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
T_{stg}	storage temperature			–55	+125	°C
P_{tot}	total power dissipation			-	125	mW
T_j	junction temperature			–40	+85	°C
$I_{i(max)}$	maximum input current	LA to LB; peak	[3]	-	±60	mA
I_I	input current	LA to LB; RMS		-	30	mA
V_{ESD}	electrostatic discharge voltage	Human body model	[4]	-	±2	kV

[1] Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the operating conditions and electrical characteristics sections of this specification is not implied.

[2] This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maxima.

[3] The voltage between LA and LB is limited by the on-chip voltage limitation circuitry (corresponding to parameter I_I).

[4] For ESD measurement, the IC was mounted in a CDIP8 package.

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11. Characteristics

11.1 Memory characteristics

Table 41. EEPROM characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_{ret}	retention time	$T_{amb} \leq 55$ °C	50	-	-	year
$N_{endu(W)}$	write endurance		100000	-	-	cycle

11.2 Interface characteristics

Table 42. Interface characteristics

Typical ratings are not guaranteed. The values listed are at room temperature.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
f_i	input frequency		[1]	13.553	13.56	13.567	MHz
$V_{i(RMS)min}$	minimum RMS input voltage	operating read/write		1.5	-	1.7	V
$P_{i(min)}$	minimum input power	operating	[2]	-	40	-	μW
C_i	input capacitance	between LA and LB	[3]				
		SL2S2002FUD SL2S2002FTB		22.3	23.5	24.7	pF
		SL2S2102FUD SL2S2102FTB		92	97	102	pF

[1] Bandwidth limitation (± 7 kHz) according to ISM band regulations.

[2] Including losses in the resonant capacitor and rectifier.

[3] Measured with an HP4285A LCR meter at 13.56 MHz and 2 V RMS.

12. Marking

12.1 Marking SOT1122

Table 43. Marking SOT1122

Type number	Marking code
SL2S2002FTB	20
SL2S2102FTB	21

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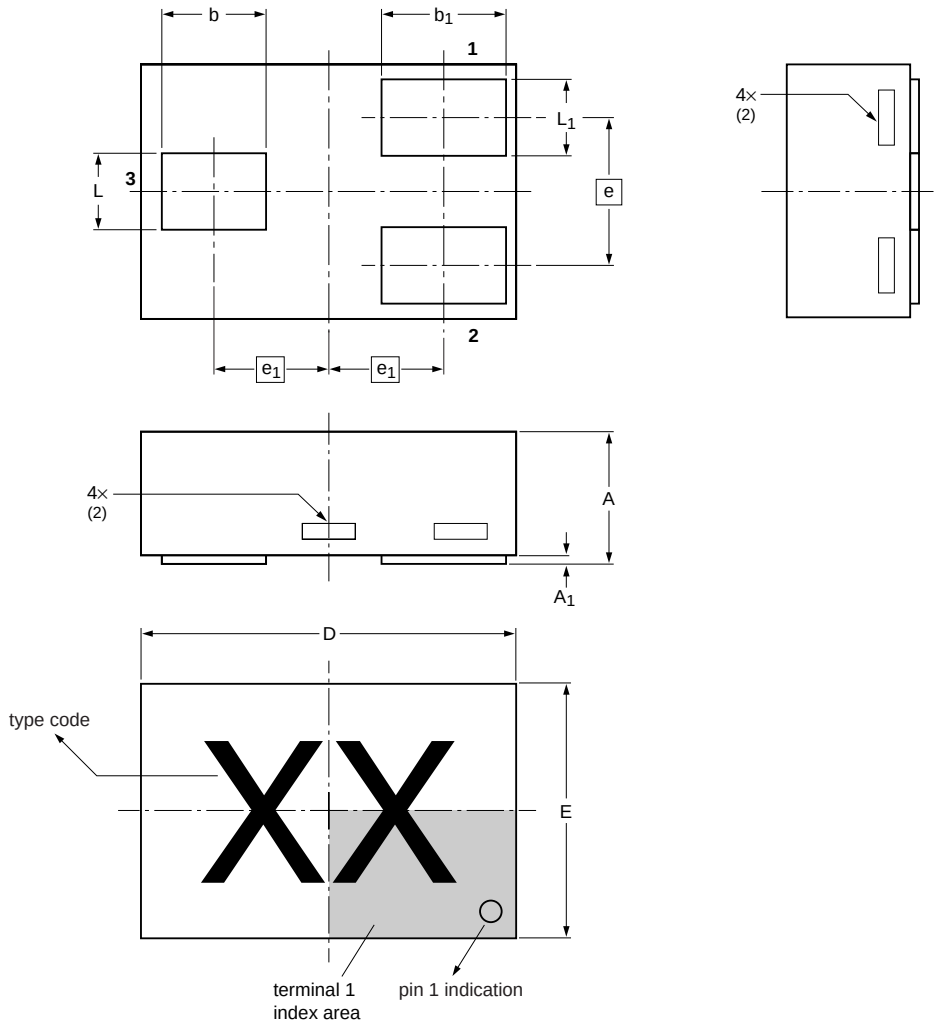
13. Package outline

XSON3: plastic extremely thin small outline package; no leads; 3 terminals; body 1 x 1.45 x 0.5 mm **SOT1122**



Dimensions

Unit		A(1)	A1	b	b1	D	E	e	e1	L	L1
	max	0.50	0.04	0.45	0.55	1.50	1.05			0.35	0.30
mm	nom			0.40	0.50	1.45	1.00	0.55	0.425	0.30	0.25
	min			0.37	0.47	1.40	0.95			0.27	0.22

Notes
1. Dimension A is including plating thickness.
2. Can be visible in some manufacturing processes.

sot1122_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1122		MO-252				09-10-09

Fig 5. Package outline SOT1122

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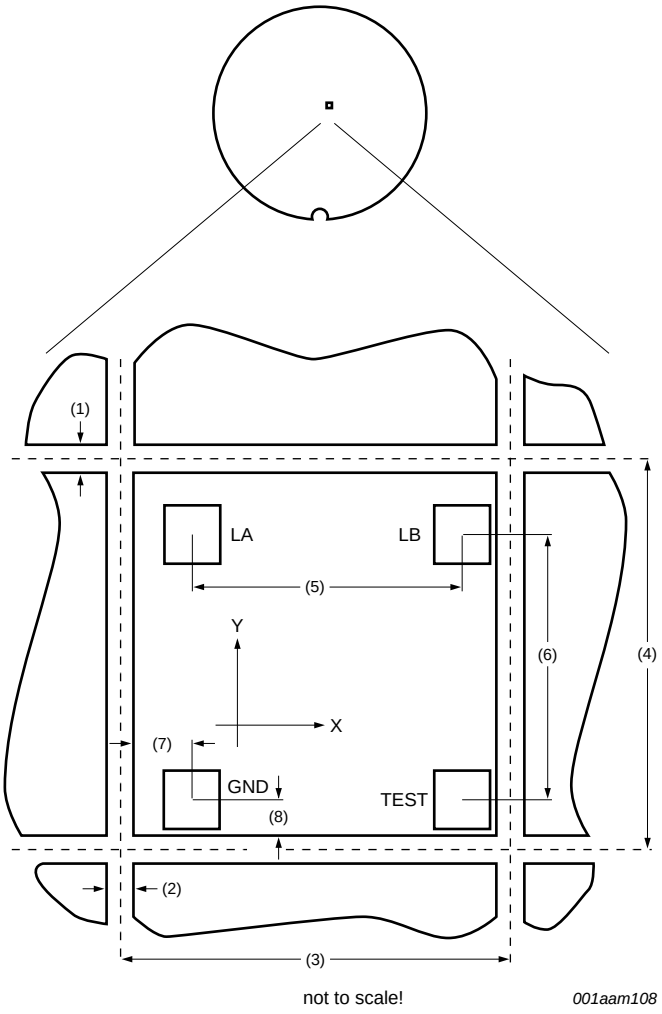
14. Bare die outline



(1) X-scribe line width: 15 μm

(2) Y-scribe line width: 15 μm

(3) Chip step, X-length: 535 μm

(4) Chip step, Y-length: 499 μm

(5) Bump to bump distance X (LA - LB): 400 μm

(6) Bump to bump distance Y (LB - TEST): 360 μm

(7) Distance bump to nitride edge X: 75 μm

(8) Distance bump to nitride edge Y: 45 μm

Bump size X × Y: 60 μm × 60 μm

Fig 6. Wafer SL2S2002FUD bare die layout

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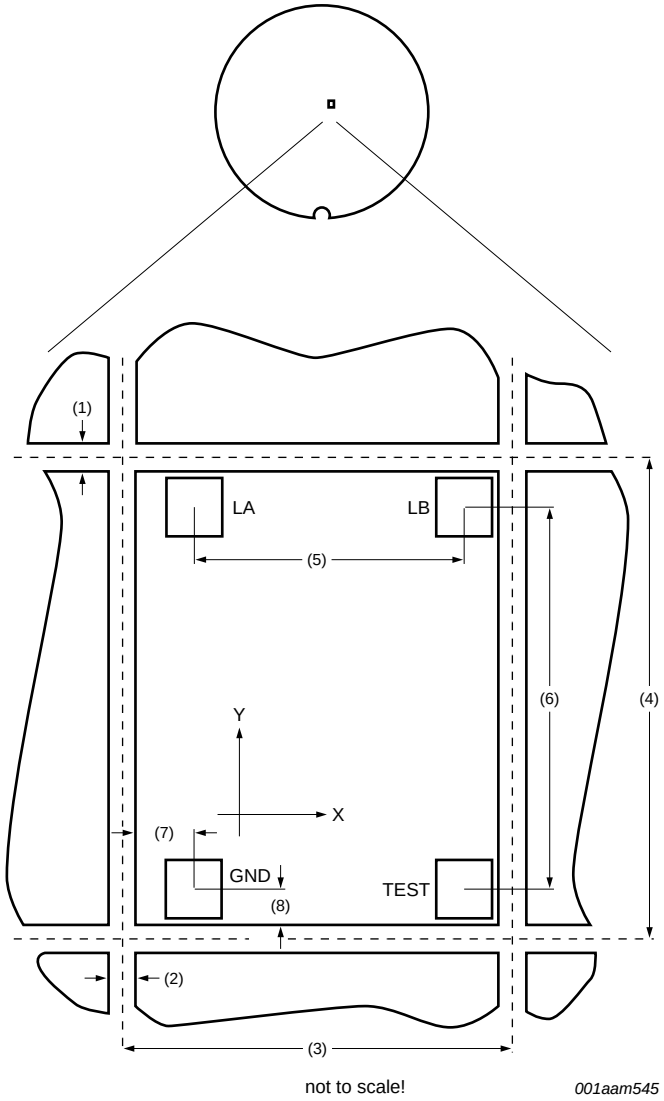

(1) X-scribe line width: 15 μm

(2) Y-scribe line width: 15 μm

(3) Chip step, X-length: 535 μm

(4) Chip step, Y-length: 622 μm

(5) Bump to bump distance X (LA - LB): 400 μm

(6) Bump to bump distance Y (LB - TEST): 517 μm

(7) Distance bump to nitride edge X: 75 μm

(8) Distance bump to nitride edge Y: 45 μm

Bump size X × Y: 60 μm × 60 μm

Fig 7. Wafer SL2S2102FUD bare die layout

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15. Abbreviations

Table 44. Abbreviations

Acronym	Description
AFI	Application Family Identifier
CRC	Cyclic Redundancy Check
DSFID	Data Storage Format Identifier
EAS	Electronic Article Surveillance
EEPROM	Electrically Erasable Programmable Read Only Memory
EOF	End Of Frame
IC	Integrated Circuit
LCR	Inductance, Capacitance, Resistance
LSB	Least Significant Byte/Bit
MSB	Most Significant Byte/Bit
RF	Radio Frequency
SOF	Start Of Frame
UID	Unique IDentifier

16. References

[1] **ISO Standard —** ISO/IEC 15693 - Identification cards - Contactless integrated circuit cards - Vicinity cards.

[2] **ISO Standard —** ISO/IEC 15693-2 -Identification cards - Contactless integrated circuit cards - Vicinity cards - Part 2: Air interface and initialization.

[3] **ISO Standard —** ISO/IEC 15693-3 -Identification cards - Contactless integrated circuit cards - Vicinity cards - Part 3: Anticollision and transmission protocol.

[4] **ISO Standard —** ISO/IEC 18000-3 - Information technology - Radio frequency identification for item management - Part 3: Parameters for air interface communications at 13.56 MHz.

[5] **ISO Standard —** ISO/IEC 7816-6 - Identification cards - Integrated circuit cards - Part 6: Interindustry data elements for interchange.

[6] **General specification for 8” wafer on UV-tape with electronic fail die marking —** Delivery type description – BL-ID document number: 1093**[1].

1. ** ... document version number

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17. Revision history

Table 45. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
SL2S2002_SL2S2102 v3.3	20120823	Product data sheet	-	SL2S2002_SL2S2102 v3.2
Modifications:	• Security level changed into “COMPANY PUBLIC”			
SL2S2002_SL2S2102 v3.2	20110110	Product data sheet	-	SL2S2002_SL2S2102 v3.1
Modifications:	• Type numbers SL2S2002FTB and SL2S2102FTB added • Section 6 “Pinning information”, Section 12 “Marking” and Section 13 “Package outline” added			
SL2S2002_SL2S2102 v3.1	20100908	Product data sheet	-	SL2S2002 v3.0
Modifications:	• Added type number SL2S2102 • Document layout updated • Table 43: symbols and parameter descriptions updated			
SL2S2002 v3.0	20100527	Product data sheet	-	178020
178020	20100430	Preliminary data sheet	-	178010
178010	20100205	Objective data sheet	-	-

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Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[2] The term 'short data sheet' is explained in section "Definitions".

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